L Number	Hits	Search Text	DB	Time stamp
1	2	5969461.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:28
2	2	6078229.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:28
3	2	6262513.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:30
4	1		USPAT	2004/09/14 13:29
5	1		USPAT	2004/09/14 13:29
6	1		USPAT	2004/09/14 13:30
7	1		USPAT	2004/09/14 13:30
8	2	6310421.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:31
9	2	6492194.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:32
10	650254	(al ceramic silicon polymer glass transparent) with (substrate carrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:33
11	134684	(surface with (acoustic acoustical acoustically wave))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:34
12	2677087	ccd semiconductor chip die (integrated adj circuit) ic dice	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:35
13	10118	(ccd semiconductor chip die (integrated adj circuit) ic dice) same ((surface with (acoustic acoustical acoustically wave)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:35
14	2853	((al ceramic silicon polymer glass transparent) with (substrate carrier)) and ((ccd semiconductor chip die (integrated adj circuit) ic dice) same ((surface with (acoustic acoustical acoustically wave))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:36
15	740	((al ceramic silicon polymer glass transparent) with (substrate carrier)) same ((ccd semiconductor chip die (integrated adj circuit) ic dice) same ((surface with (acoustic acoustical acoustically wave))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:36

16	170414	(edge end outer corner border) with (buffer buffering buffered polymer organic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:38
17	2	(((al ceramic silicon polymer glass transparent) with (substrate carrier)) same ((ccd semiconductor chip die (integrated adj circuit) ic dice) same ((surface with (acoustic acoustical acoustically wave))))) same ((edge end outer corner border) with (buffer buffering buffered polymer organic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:39
18	176	(((al ceramic silicon polymer glass transparent) with (substrate carrier)) and ((ccd semiconductor chip die (integrated adj circuit) ic dice) same ((surface with (acoustic acoustical acoustically wave))))) and ((edge end outer corner border) with (buffer buffering buffered polymer organic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:42
19	701717	bump ball bga fhipchip (flip adj3 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:42
20	701778	bump ball bga flipchip (flip adj3 chip)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:43
21	81428	(ccd semiconductor chip die (integrated adj circuit) ic dice) same (bump ball bga flipchip (flip adj3 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:44
22	13120	((al ceramic silicon polymer glass transparent) with (substrate carrier)) same (bump ball bga flipchip (flip adj3 chip))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:45
23	539	(((al ceramic silicon polymer glass transparent) with (substrate carrier)) same (bump ball bga flipchip (flip adj3 chip))) and ((surface with (acoustic acoustical acoustically wave)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:45
24	53	((((al ceramic silicon polymer glass transparent) with (substrate carrier)) same (bump ball bga flipchip (flip adj3 chip))) and ((surface with (acoustic acoustical acoustically wave)))) and ((edge end outer corner border) with (buffer buffering buffered polymer organic))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/14 13:45

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